



Semiconductor Device Type: D8X TSSOP-16-4.4mm-MatteTin						Package Homogeneous Materials					
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	22.50	(mg) Total	Mold Compound	% of Total Weight	34.62	
Silica, vitreous (or fused)	60676-86-0	Mold Compound	29.43	19.13	294270		Silica, vitreous (or fused)	60676-86-0	85.00		
Epoxy Resin	Trade Secret	Mold Compound	3.01	1.96	30119		Epoxy Resin	Trade Secret	8.70		
Phenolic Resin	Trade Secret	Mold Compound	2.08	1.35	20772		Phenolic Resin	Trade Secret	6.00		
Carbon Black	1333-86-4	Mold Compound	0.10	0.07	1039		Carbon Black	1333-86-4	0.30		
Copper	7440-50-8	Lead Frame	44.47	28.90	444680		Total			100.00	
Nickel	7440-02-0	Lead Frame	1.19	0.77	11859						
Silver	7440-22-4	Lead Frame	0.78	0.51	7793	30.35	(mg) Total	Lead Frame	% of Total Weight	46.69	
Silicon	7440-21-3	Lead Frame	0.21	0.14	2101		Copper	7440-50-8	95.24		
Magnesium	7439-95-4	Lead Frame	0.05	0.03	467		Nickel	7440-02-0	2.54		
Silver	7440-22-4	Die Attach	2.47	1.61	24716		Silver	7440-22-4	1.67		
Epoxy resin	Trade Secret	Die Attach	0.67	0.43	6680		Silicon	7440-21-3	0.45		
Metal oxide	Trade Secret	Die Attach	0.10	0.07	1002		Magnesium	7439-95-4	0.10		
Gamma-butyrolactone	96-48-0	Die Attach	0.10	0.07	1002		Total			100.00	
Silicon	7440-21-3	Die	12.34	8.02	123400						
Gold	7440-57-5	Wire Bond	0.61	0.40	6100	2.17	(mg) Total	Die Attach	% of Total Weight	3.34	
Tin	7440-31-5	Plating on external leads	2.40	1.56	24000		Silver	7440-22-4	74.00		
65.00 mg Total Mass			TOTALS:	100.00	65.00	1,000,000		Epoxy resin	Trade Secret	20.00	
								Metal oxide	Trade Secret	3.00	
								Gamma-butyrolactone	96-48-0	3.00	
								Total			100.00
							8.02	(mg) Total	Die	% of Total Weight	12.34
								Silicon	7440-21-3	100.00	
								Total			100.00
							0.40	(mg) Total	Wire Bond	% of Total Weight	0.61
								Gold	7440-57-5	100.00	
								Total			100.00
							1.56	(mg) Total	Plating on external leads	% of Total Weight	2.40
								Tin	7440-31-5	100.00	
							65.00	Total		100.00	100.00

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